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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 660K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as066n4f40i3sg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Market	Applications
Wireless	Channel and switch cards in remote radio heads Mobile backhaul
Wireline	 40G/100G muxponders and transponders 100G line cards Bridging Aggregation
Broadcast	 Studio switches Servers and transport Videoconferencing Professional audio and video
Computing and Storage	Flash cache Cloud computing servers Server acceleration
Medical	Diagnostic scanners Diagnostic imaging
Military	Missile guidance and control Radar Electronic warfare Secure communications

Related Information

Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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Key Advantages of Intel Arria 10 Devices

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	Built on TSMC's 20 nm process technology 60% higher performance than the previous generation of mid-range FPGAs 15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	 Short-reach rates up to 25.8 Gigabits per second (Gbps) Backplane capability up to 12.5 Gbps Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)
Improved logic integration and hard IP blocks	8-input adaptive logic module (ALM) Up to 65.6 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks Fractional synthesis phase-locked loops (PLLs) Hard PCI Express Gen3 IP blocks Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs

Summary of Intel Arria 10 Features

 Table 3.
 Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	 TSMC's 20-nm SoC process technology Allows operation at a lower V_{CC} level of 0.82 V instead of the 0.9 V standard V_{CC} core voltage
Packaging	 1.0 mm ball-pitch Fineline BGA packaging 0.8 mm ball-pitch Ultra Fineline BGA packaging Multiple devices with identical package footprints for seamless migration between different FPGA densities Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices RoHS, leaded⁽¹⁾, and lead-free (Pb-free) options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved multi-track routing architecture to reduce congestion and improve compilation time Hierarchical core clocking architecture Fine-grained partial reconfiguration
Internal memory blocks	M20K—20-Kb memory blocks with hard error correction code (ECC) Memory logic array block (MLAB)—640-bit memory
	continued

⁽¹⁾ Contact Intel for availability.



Feature	Description
	 Dynamic reconfiguration of the transceivers and PLLs Fine-grained partial reconfiguration of the core fabric Active Serial x4 Interface
Power management	SmartVID Low static power device options Programmable Power Technology Intel Quartus Prime integrated power analysis
Software and tools	 Intel Quartus Prime design suite Transceiver toolkit Platform Designer system integration tool DSP Builder for Intel FPGAs OpenCL™ support Intel SoC FPGA Embedded Design Suite (EDS)

Related Information

Intel Arria 10 Transceiver PHY Overview

Provides details on Intel Arria 10 transceivers.

Intel Arria 10 Device Variants and Packages

Table 4. **Device Variants for the Intel Arria 10 Device Family**

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	 FPGA featuring: 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability. 25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

Intel Arria 10 GX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line	
		GX 570	GX 660	GX 900	GX 1150
Logic Elements	s (LE) (K)	570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precision DSP Block		1,523	1,687	1,518	1,518
18 x 19 Multip	lier	3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Trai	nsceiver	48	48	96	96
GPIO (3)		696	696	768	768
LVDS Pair (4)		324	324	384	384
PCIe Hard IP Block		2	2	4	4
Hard Memory	Controller	16	16	16	16

Package Plan

Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line		U19 F27 (19 mm × 19 mm, 484-pin UBGA) (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 160	48	192	6	48	192	12	48	240	12
GX 220	48	192	6	48	192	12	48	240	12
GX 270	_	_	_	48	192	12	48	312	12
GX 320	_	_	_	48	192	12	48	312	12
GX 480	_	_	_	_	_	_	48	312	12



Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)		F35 (35 mm × 35 mm, 1152-pin FBGA)		KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	_	_	_	_	_
GX 320	48	336	24	48	336	24	_	_	_	_	_	_
GX 480	48	444	24	48	348	36	_	_	_	_	_	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	_	504	24	_	_	_	_	_	_	_	600	48
GX 1150	_	504	24	_	_	_	_	_	_	_	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)		NF45 (45 mm × 45 mm) 1932-pin FBGA)		SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 900	_	342	66	_	768	48	-	624	72	_	480	96
GX 1150	_	342	66	_	768	48	ı	624	72	ı	480	96

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	ource	Produc	ct Line
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register		1,358,480	1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 ⁽⁵⁾	72 ⁽⁵⁾
	25.8 Gbps	6	6
GPIO ⁽⁶⁾		624	624
LVDS Pair ⁽⁷⁾		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11. Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)					
	3 V I/O	LVDS I/O	XCVR			
GT 900	_	624	72			
GT 1150	_	624	72			

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.

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Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources	
Medium precision fixed point	Two 18 x 19	1	
High precision fixed or Single precision floating point	One 27 x 27	1	
Fixed point FFTs	One 19 x 36 with external adder	1	
Very high precision fixed point	One 36 x 36 with external adder	2	
Double precision floating point	One 54 x 54 with external adder	4	

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant Pro	Product Line Variable- precision		Independent Input and Output Multiplications Operator		18 x 19 Multiplier	18 x 18 Multiplier
	DSP Block	DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Adder Sum Mode	Adder Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	GT 900	1,518	3,036	1,518	1,518	1,518
GT	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



Embedded Memory Configurations for Single-port Mode

Table 19. Single-port Embedded Memory Configurations for Intel Arria 10 Devices

This table lists the maximum configurations supported for single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width	
MLAB	32	x16, x18, or x20	
	64 (10)	x8, x9, x10	
M20K	512	x40, x32	
	1K	x20, x16	
	2K	x10, x8	
	4K	x5, x4	
	8K	x2	
	16K	x1	

Clock Networks and PLL Clock Sources

The clock network architecture is based on Intel's global, regional, and peripheral clock structure. This clock structure is supported by dedicated clock input pins, fractional clock synthesis PLLs, and integer I/O PLLs.

Clock Networks

The Intel Arria 10 core clock networks are capable of up to 800 MHz fabric operation across the full industrial temperature range. For the external memory interface, the clock network supports the hard memory controller with speeds up to 2,400 Mbps in a quarter-rate transfer.

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.

Fractional Synthesis and I/O PLLs

Intel Arria 10 devices contain up to 32 fractional synthesis PLLs and up to 16 I/O PLLs that are available for both specific and general purpose uses in the core:

- Fractional synthesis PLLs—located in the column adjacent to the transceiver blocks
- I/O PLLs-located in each bank of the 48 I/Os

Fractional Synthesis PLLs

You can use the fractional synthesis PLLs to:

- Reduce the number of oscillators that are required on your board
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

⁽¹⁰⁾ Supported through software emulation and consumes additional MLAB blocks.

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The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



- Series (R_S) and parallel (R_T) on-chip termination (OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

External Memory Interface

Intel Arria 10 devices offer massive external memory bandwidth, with up to seven 32-bit DDR4 memory interfaces running at up to 2,400 Mbps. This bandwidth provides additional ease of design, lower power, and resource efficiencies of hardened high-performance memory controllers.

The memory interface within Intel Arria 10 FPGAs and SoCs delivers the highest performance and ease of use. You can configure up to a maximum width of 144 bits when using the hard or soft memory controllers. If required, you can bypass the hard memory controller and use a soft controller implemented in the user logic.

Each I/O contains a hardened DDR read/write path (PHY) capable of performing key memory interface functionality such as read/write leveling, FIFO buffering to lower latency and improve margin, timing calibration, and on-chip termination.

The timing calibration is aided by the inclusion of hard microcontrollers based on Intel's Nios® II technology, specifically tailored to control the calibration of multiple memory interfaces. This calibration allows the Intel Arria 10 device to compensate for any changes in process, voltage, or temperature either within the Intel Arria 10 device itself, or within the external memory device. The advanced calibration algorithms ensure maximum bandwidth and robust timing margin across all operating conditions.

In addition to parallel memory interfaces, Intel Arria 10 devices support serial memory technologies such as the Hybrid Memory Cube (HMC). The HMC is supported by the Intel Arria 10 high-speed serial transceivers which connect up to four HMC links, with each link running at data rates up to 15 Gbps.

Related Information

External Memory Interface Spec Estimator

Provides a parametric tool that allows you to find and compare the performance of the supported external memory interfaces in IntelFPGAs.

Memory Standards Supported by Intel Arria 10 Devices

The I/Os are designed to provide high performance support for existing and emerging external memory standards.



Related Information

Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

PCS Features on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

PCS Features on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.

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The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed







Transceiver Channels

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other preprocessing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.





PCS	Description
Standard PCS	 Operates at a data rate up to 12 Gbps Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.
Enhanced PCS	 Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA Handles data transfer to and from the FPGA fabric Handles data transfer internally to and from the PMA Provides frequency compensation Performs channel bonding for multi-channel low skew applications
PCIe Gen3 PCS	 Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates Provides support for PIPE 3.0 features Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed

Related Information

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

PCS Protocol Support

This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
	•		continued



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI $^{\text{\tiny M}}$) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows
 the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is
 primarily used for control and status register (CSR) accesses to peripherals in the
 FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux*, VxWorks*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.

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Date	Version	Changes
		 Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from Sample Ordering Core and Available Options for Intel Arria 10 GT Devices figure. Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps. Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from PMA Features of the Transceivers in Intel Arria 10 Devices table.
September 2017	2017.09.20	Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.
July 2017	2017.07.13	Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".
July 2017	2017.07.06	Added automotive temperature option to Intel Arria 10 GX device family.
May 2017	2017.05.08	Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants. Removed all "Preliminary" marks.
March 2017	2017.03.15	 Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel.
October 2016	2016.10.31	 Removed package F36 from Intel Arria 10 GX devices. Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.
May 2016	2016.05.02	 Updated the FPGA Configuration and HPS Booting topic. Remove V_{CC} PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.
February 2016	2016.02.11	 Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally. Revised the state for Core clock networks in the Summary of Features topic. Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table. Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table. Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table. Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure. Changed transceiver parameters in the "Low Power Serial Transceivers" section. Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table. Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure. Changed the datarates for GT devices in the "PMA Features" section.